MOSFETs Silicon N-channel MOS (U-MOSX-H)

TK2R4A08QM

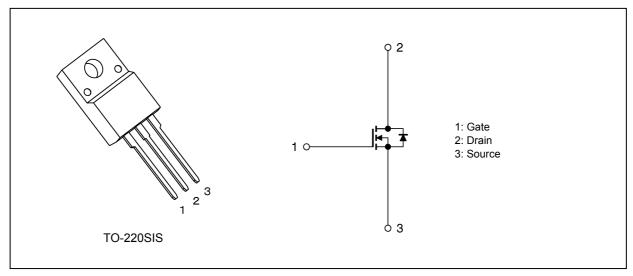
1. Applications

- High-Efficiency DC-DC Converters
- Switching Voltage Regulators
- Motor Drivers

2. Features

- (1) High-speed switching
- (2) Small gate charge: $Q_{SW} = 54 \text{ nC}$ (typ.)
- (3) Small output charge: $Q_{oss} = 210 \text{ nC}$ (typ.)
- (4) Low drain-source on-resistance: $R_{DS(ON)} = 1.88 \text{ m}\Omega$ (typ.) ($V_{GS} = 10 \text{ V}$)
- (5) Low leakage current: $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 80 \ V)$
- (6) Enhancement mode: V_{th} = 2.5 to 3.5 V (V_{DS} = 10 V, I_D = 2.2 mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) ($T_a = 25 \ ^{\circ}C$ unless otherwise specified)

Characteristi	Symbol	Rating	Unit		
Drain-source voltage			V _{DSS}	80	V
Gate-source voltage			V _{GSS}	±20]
Drain current (DC)	(T _c = 25 °C)	(Note 1)	Ι _D	100	A
Drain current (DC)	(Silicon limit)	(Note 1), (Note 2)	Ι _D	116]
Drain current (pulsed)	(t = 100 μs)	(Note 1)	I _{DP}	500	
Power dissipation	(T _c = 25 °C)		PD	47	W
Single-pulse avalanche energy		(Note 3)	E _{AS}	143	mJ
Single-pulse avalanche current		(Note 3)	I _{AS}	100	A
Channel temperature			T _{ch}	175	ů
Storage temperature	·		T _{stg}	-55 to 175	
Isolation voltage (RMS)	(t = 1.0 s)		V _{ISO(RMS)}	2000	V
Mounting torque			TOR	0.6	N · m

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristic	S	Symbol	Max	Unit
Channel-to-case thermal resistance	(T _c = 25 °C)	R _{th(ch-c)}	3.19	°C/W
Channel-to-ambient thermal resistance	(T _a = 25 °C)	R _{th(ch-a)}	62.5	

Note 1: Ensure that the channel temperature does not exceed 175 °C.

Note 2: Limited 100 A by package capability.

Note 3: V_DD = 64 V, T_ch = 25 °C (initial), L = 11 μ H, I_{AS} = 100 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics ($T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	V_{GS} = ±20 V, V_{DS} = 0 V	_	_	±0.1	μA
Drain cut-off current	I _{DSS}	V _{DS} = 80 V, V _{GS} = 0 V	_	_	10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	80	_	—	V
Drain-source breakdown voltage (Note 4)	V _{(BR)DSX}	I _D = 10 mA, V _{GS} = -20 V	60	_	_	
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 2.2 mA	2.5	_	3.5	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 6 V, I _D = 50 A	_	2.3	3.1	mΩ
		V _{GS} = 10 V, I _D = 50 A		1.88	2.44	

Note 4: If a reverse bias is applied between gate and source, this device enters V_{(BR)DSX} mode. Note that the drainsource breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 40 V, V _{GS} = 0 V, f = 1 MHz	_	13000	—	pF
Reverse transfer capacitance	C _{rss}		_	135	_	
Output capacitance	C _{oss}		_	3200	—	
Gate resistance	r _g	—	_	1.9	2.9	Ω
Switching time (rise time)	tr	See Fig. 6.2.1	—	91	—	ns
Switching time (turn-on time)	t _{on}		_	119	—	
Switching time (fall time)	t _f		_	95	—	
Switching time (turn-off time)	t _{off}		_	251	_	

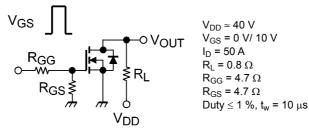


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics ($T_a = 25$ °C unless otherwise specified)

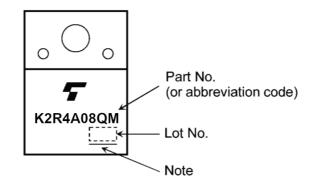
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	Qg	$V_{DD} \approx 40$ V, V_{GS} = 10 V, I_D = 50 A	_	179	_	nC
gate-drain)		$V_{DD} \approx 40$ V, V_{GS} = 6 V, I_D = 50 A	_	102	—	
Gate-source charge 1	Q _{gs1}	$V_{DD} \approx 40$ V, V_{GS} = 10 V, I_D = 50 A	_	51	_	
Gate-drain charge	Q _{gd}		_	38	_	
Gate switch charge	Q _{SW}		_	54	—	
Output charge	Q _{oss}	V _{DS} = 40 V, V _{GS} = 0 V, f = 1 MHz	_	210	_	

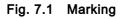
6.4. Source-Drain Characteristics ($T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Note 5)	I _{DRP}	t = 100 μs	_	_	500	A
Diode forward voltage	V _{DSF}	I _{DR} = 50 A, V _{GS} = 0 V	_	_	-1.2	V
Reverse recovery time	t _{rr}	I _{DR} = 25 A, V _{GS} = 0 V,	_	66	_	ns
Reverse recovery charge	Q _{rr}	-dI _{DR} /dt = 100 A/µs	_	100	_	nC

Note 5: Ensure that the channel temperature does not exceed 175 °C.

7. Marking (Note)





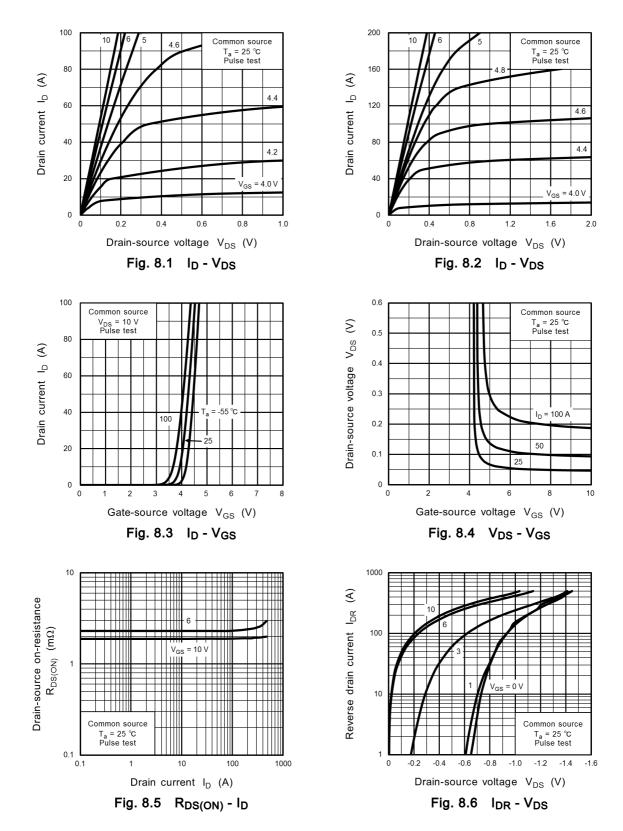
Note: A line under a Lot No. identifies the indication of product Labels. Not underlined: [[Pb]]/INCLUDES > MCV

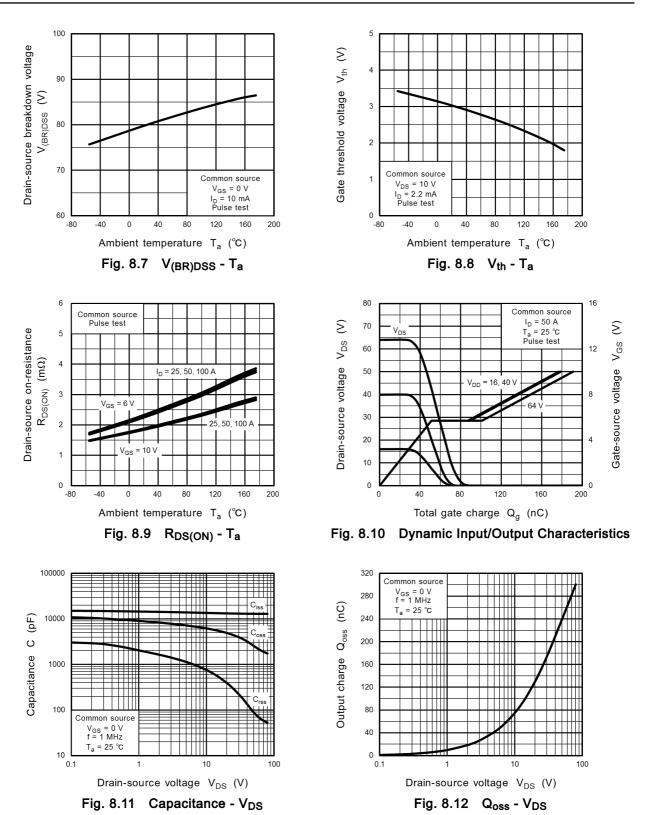
Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

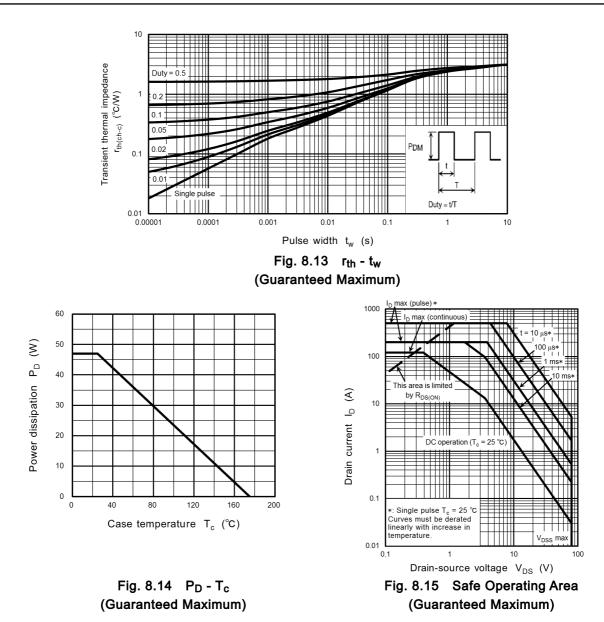
The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

8. Characteristics Curves (Note)





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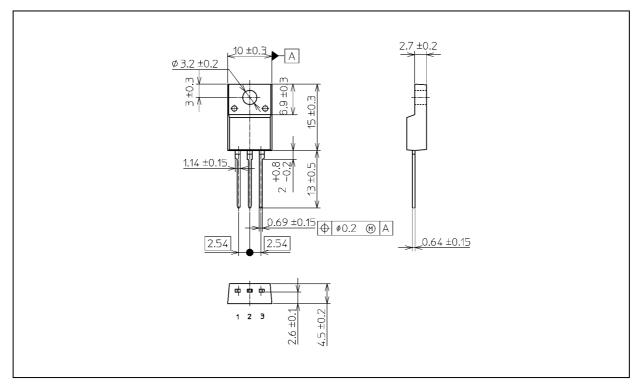


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

TK2R4A08QM

Package Dimensions

Unit: mm



Weight: 1.56 g (typ.)

Package Name(s)
TOSHIBA: 2-10U1S
Nickname: TO-220SIS

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